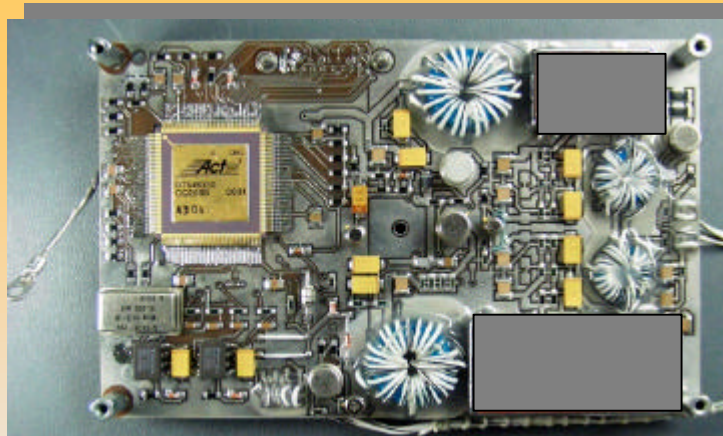
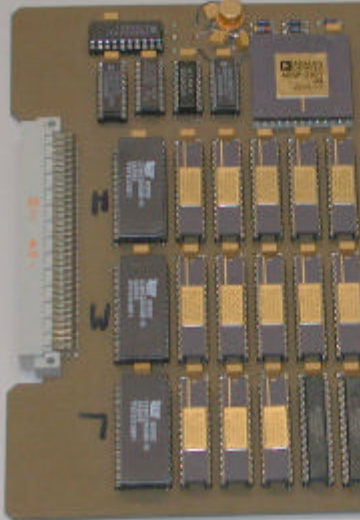


# DATA HANDLING: Main DPUs inheritances

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## FORMER AMDL's related experiences:

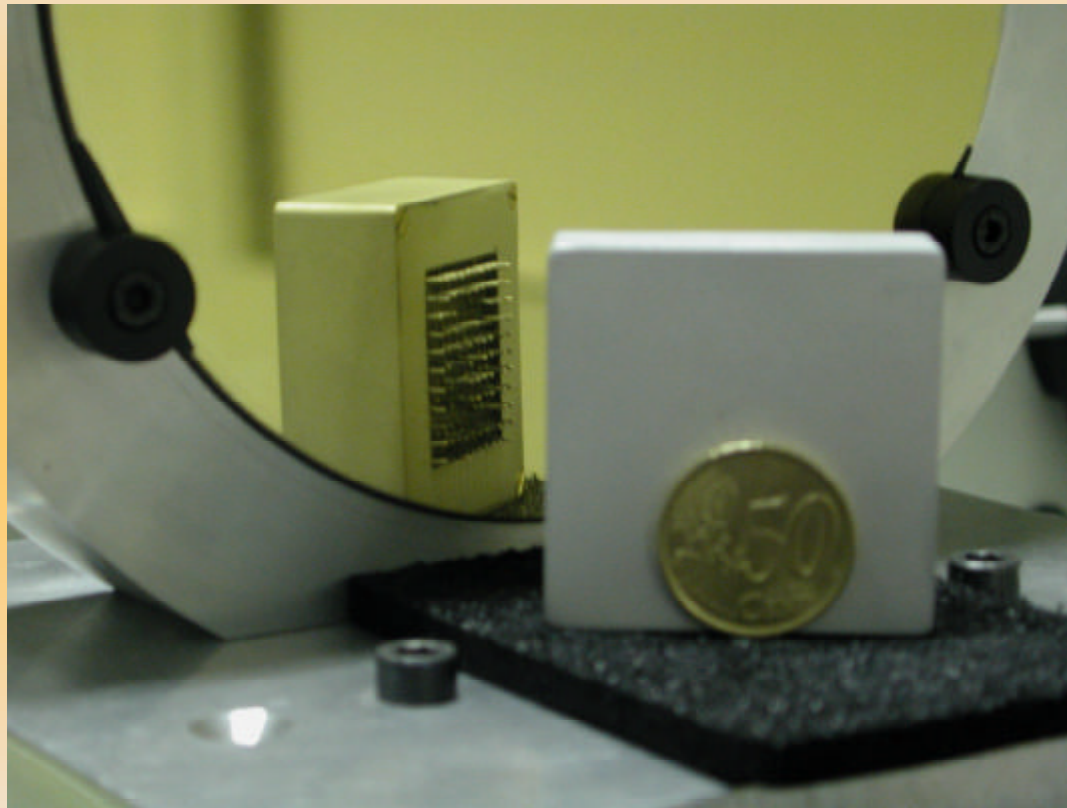
- CLUSTER: CIS-2 DPU Designing & On-Board S/W (MAS281)
- DARA-NASA EQUATOR-S: ESIC - On-Board S/W (MAS281)
- MARS-96 & ESA MARSEXRESS: PFS - FFT DPU Design & On-Board S/W (AD21000)
- DOUBLE STAR Composition Experiment OnBoard S/W (MAS281)
- ESA SMART-1: AMIE Microcamera - Power supply & S/C I/F board
- NASA/JPL DAWN: VIR On board compression S/W & GSE



# 3D technologies for main DPU

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PRESENT AMDL's technology: the 3<sup>CUBE</sup> uDSP based DPU



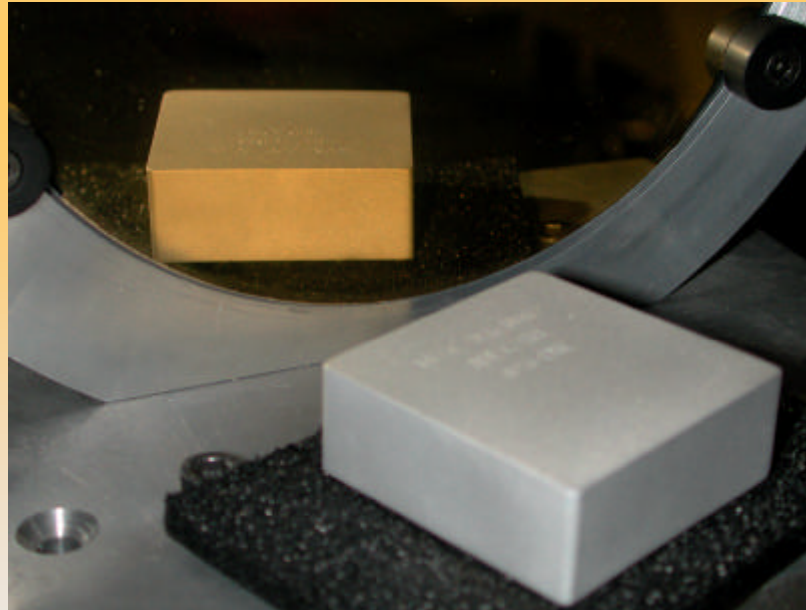
# 3<sup>Cube</sup> Main DPU Features

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## Key Features of the proposed 3<sup>Cube</sup> MINI-DPU

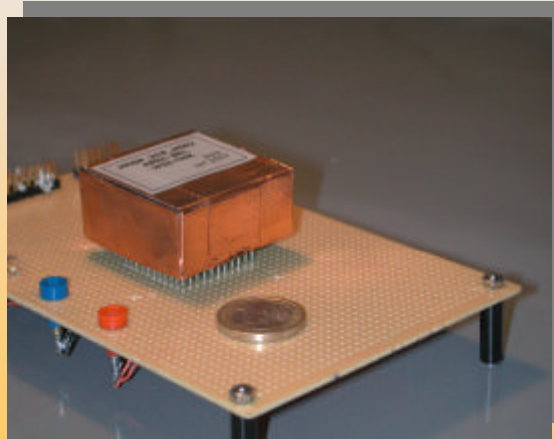
The 3<sup>Cube</sup> MINI-DPU has the following features:

- DSP operating up to 200 MHz (*Model 3MD-G*) or up to 120 MHz (*Model 3MD-P*)
- 4 Meg x 16 DRAM
- 1 Meg x 16 Flash Memory
- 32 Kilobyte SPI Flash Memory
- 10k gates customer programmable FPGA for user target I/F
- Universal Serial Bus (USB) interface
- Media Card MMC<sup>TM</sup> and Memory Stick MS<sup>TM</sup> interfaces
- Embedded 1149.1 JTAG Emulation
- I<sup>2</sup> bus I/F
- 3 x 100Mbit/s bidirectional serial buses
- +5 volt operations
- Up to 4x10 bit ADC channels
- PGA100, 0.1" pitch 100 pin interface



# 3Cube DPU lab tests gallery

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(TOP) uDPU model MDSP\_3CB\_M002 with a thermal cover.

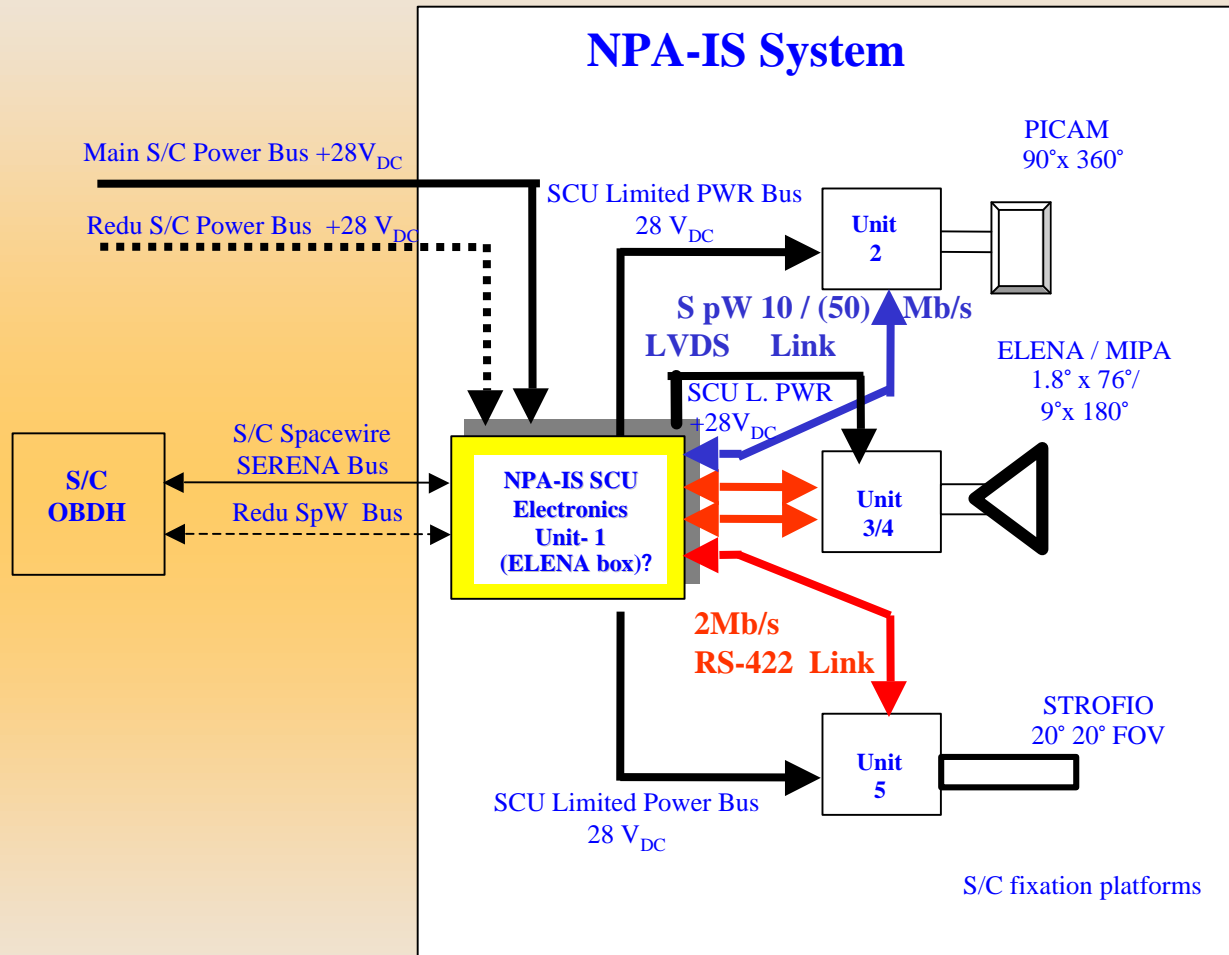
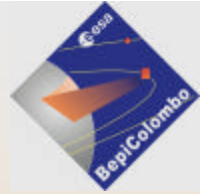


(LEFT) uDPU during memory test (500 mW on primary). (RIGHT) uDPU in stand-by (100mW on primary).

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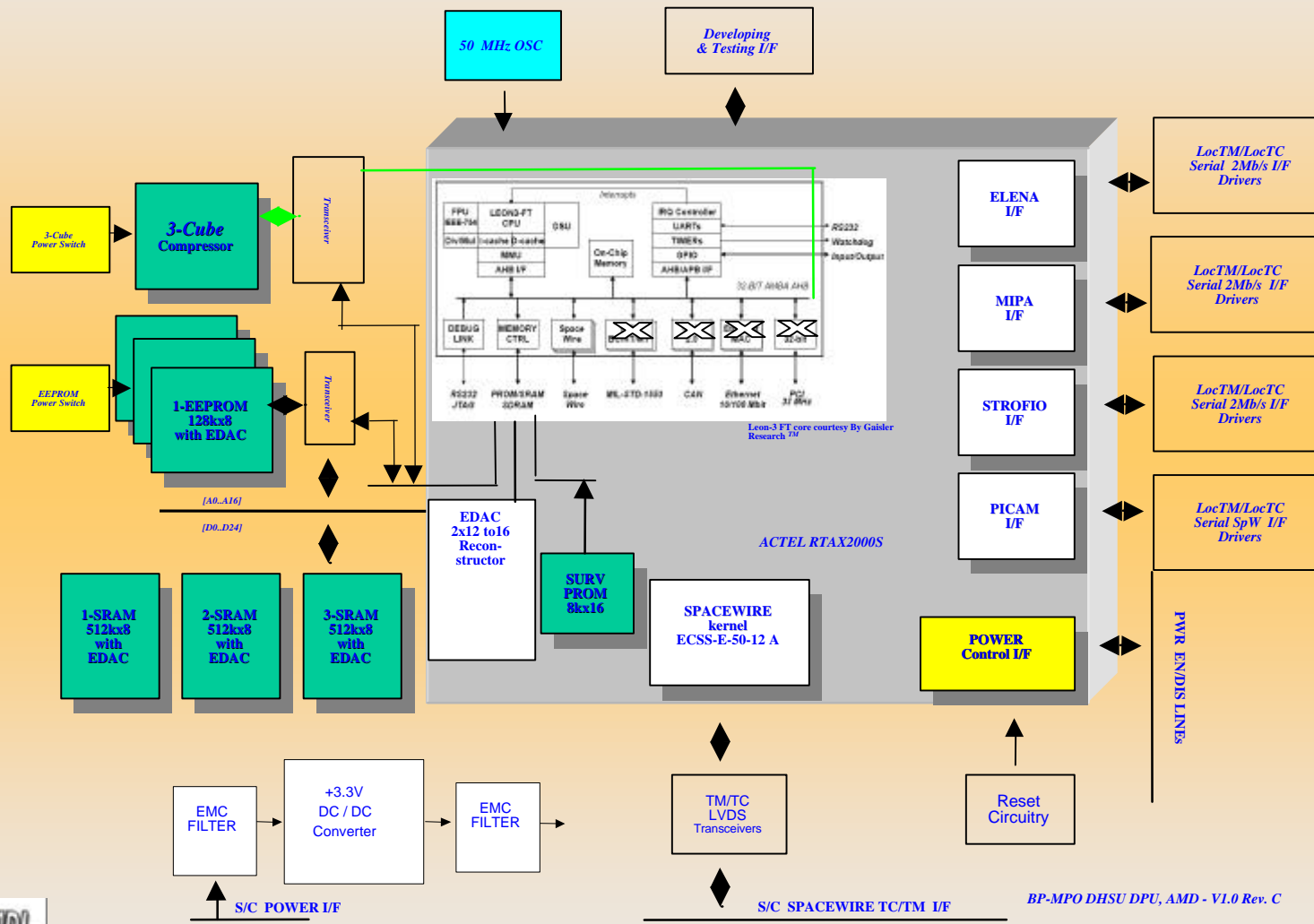
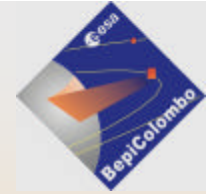


# THE SERENA DHSU on BEPICOLOMBO





# DHSU Block Diagram



BP-MPO DHSU DPU, AMD - V1.0 Rev. C

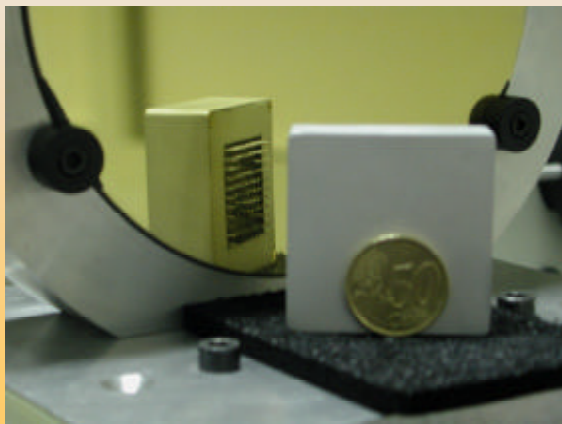


amdlspace@gmail.com

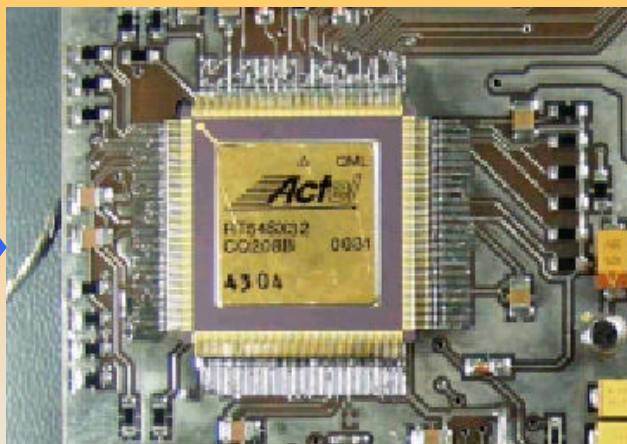


# DPU Main Electronics parts

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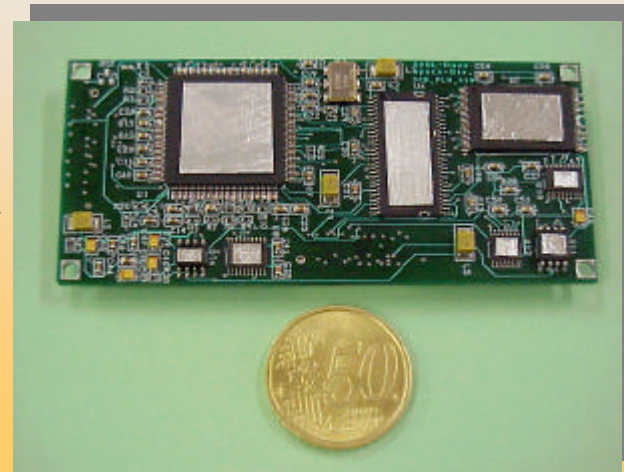
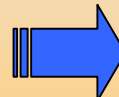


**AMDL's MDSP\_3CB\_M003**



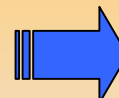
**ACTEL HI-REL RT54SX72S**

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**AMDL's 3CB\_PLN\_010  
RTAX-S RadTolerant FPGAs**

- Immune to Single-Event Upsets (SEU) to LETth > 60 MeV-cm<sup>2</sup>/mg
- Single-Event Latch-Up Immunity (SEL) to LETth >104 MeV-cm<sup>2</sup>/mg
- Functional at 300 krad (Si) Total Ionizing Dose (TID) (Projected)
- SEU Rate < 10-10 Errors/Bit-Day in Worst-Case (Geosynchronous Orbit)
- Equivalent System gates up to 2,000,000



# DSP Compressor facts

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## Compressor Core:

**3<sup>CUBE</sup> Planar model fully operated on Apr the 2<sup>nd</sup> 2004:**

- **Used within ESA Venus's DALOMIS ITT( 17946 /'03/NPLA, Sub contract DCC-LA-BN-293-04)  
Delivered 1st DALOMIS complete DHSU demonstrator**
- **Delivered DHSU demonstrator for an ISS High Energy application (SiRAD Sub.Con 745/2003 - 20/10/2003)**
- **Delivered DHSU 2xFM SiRAD models (Sub.Con IH.26 / 270223 - 12/12/2007)**
- **I/F'ed to a high DAQ Lab Applic. - 6xChs 30MS/s pipe and to USB 2.0 - 480Mb/s host I/F**



**Weight 16.9 g!**